CLAIMS

1. A resin molding apparatus for resin-molding one side face of a work in a molding die set, which resin-molds the work in a clamping state and in which the work is sucked and held on at least one of clamping faces and resin-molded in a cavity concave section whose outside dimension is larger than that of the work,

said resin molding apparatus comprising:

the molding die set including a film sucking hole, which is formed in at least one of the clamping faces, a work drawing hole, which is separated from the film sucking hole and which is communicated with a work sucking hole of the release film when the release film is sucked and held, and a cavity concave section, into which resin for molding the work is supplied;

conveying means for conveying the work into the molding die set so as to suck the other side face of the work through the work sucking hole of the release film and hold the work on one of the clamping faces, and taking out a molded product from the molding die set; and

peeling means for peeling the release film, which has stuck on the molded product, from the molded product after the molding die set is opened.

2. The resin molding apparatus according to claim 1, further comprising a guide member for guiding the outer periphery of the work, the guide member being provided in a work mounting face of one of the clamping faces and capable of projecting and retracting from the work mounting face.